

Serial No. 09/593,891
Docket No. NEC DP-624
Amendment H Under Rule 116

AMENDMENTS TO THE CLAIMS:

Kindly cancel claims 1-8 and 12, and amend claims 14, 16 and 17, as shown below.

This listing of claims will replace all prior versions and listings of claims in the Application:

Claims 1-8 (canceled)

Claim 9 (previously presented): A semiconductor device, comprising:

a package substrate having a first pad;
a first chip having a second pad and formed on said package substrate;
a wiring substrate formed on said first chip, said wiring substrate having a third pad, a fourth pad and a wiring pattern connected between said third and fourth pads; and
a second chip having a fifth pad and formed on said wiring substrate;
a first bonding wire connecting said first pad and said third pad; and
a second bonding wire connecting said fourth pad and said fifth pad.

Claim 10 (canceled)

Claim 11 (previously presented): The semiconductor device as claimed in claim 9, wherein no bonding wire connects said first pad and said fifth pad.

Claim 12 (canceled)

Claim 13 (previously presented): The device as claimed in claim 9, said device further comprising a third bonding wire connecting said first pad, wherein said third bonding wire and said first bonding wire are connected with the same first pad.

Claim 14 (currently amended): The device as claimed in claim [[12]] 9, said device comprising:

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[[a]] said package substrate having a plurality of said first pads;

[[a]] said first chip having a plurality of said second pads [[and]] formed on said package substrate;

[[a]] said wiring substrate formed on said first chip, ~~said wiring substrate~~ having a plurality of said third pads, a plurality of said fourth pads and wiring patterns connected between said third and fourth pads; and

[[a]] said second chip having a plurality of said fifth pads [[and]] formed on said wiring substrate, ~~wherein said third pads are in direct contact with said second pads.~~

Claim 15 (previously presented): The semiconductor device as claimed in claim 14, wherein one of said first pads is connected to one of said second pads as well as one of said third pads.

Claim 16 (currently amended): A stacked semiconductor storage device as claimed in claim [[12]] 9, wherein said wiring substrate is a sheet wiring substrate.

Claim 17 (currently amended): A stacked semiconductor storage device as claimed in claim [[12]] 9, wherein said wiring substrate is a board wiring substrate.

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